

ABSTRACT

An epoxy resin composition for encapsulating semiconductors containing an epoxy resin, a phenol resin, an inorganic filler, a curing accelerator, a glycerol tri-fatty acid ester produced by dehydration condensation reaction of glycerol and a saturated fatty acid with a carbon atom content of 24-36, and a hydrotalcite compound as essential components is provided. The resin composition exhibits excellent mold releasability and produces only a slight amount of stains on the surfaces of the mold and semiconductor packages. A semiconductor device exhibiting excellent solder resistance is also provided.